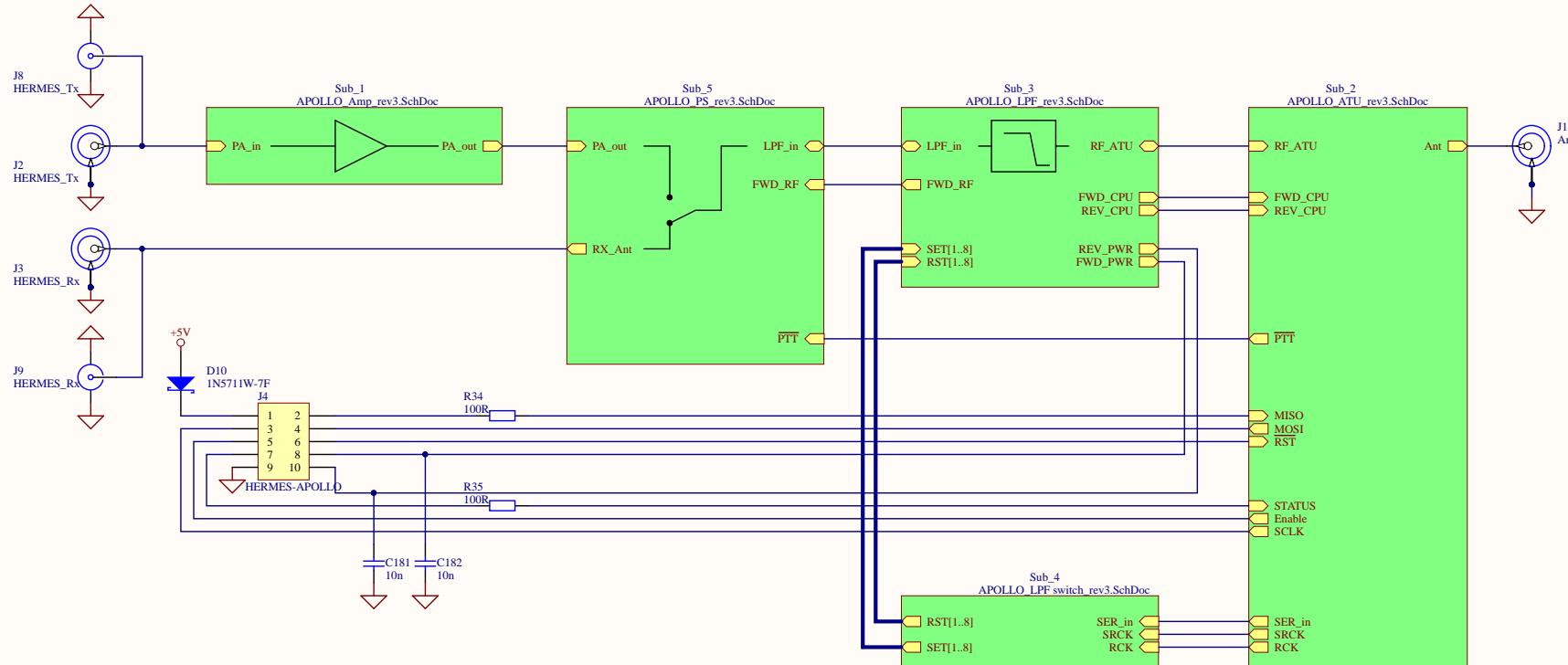
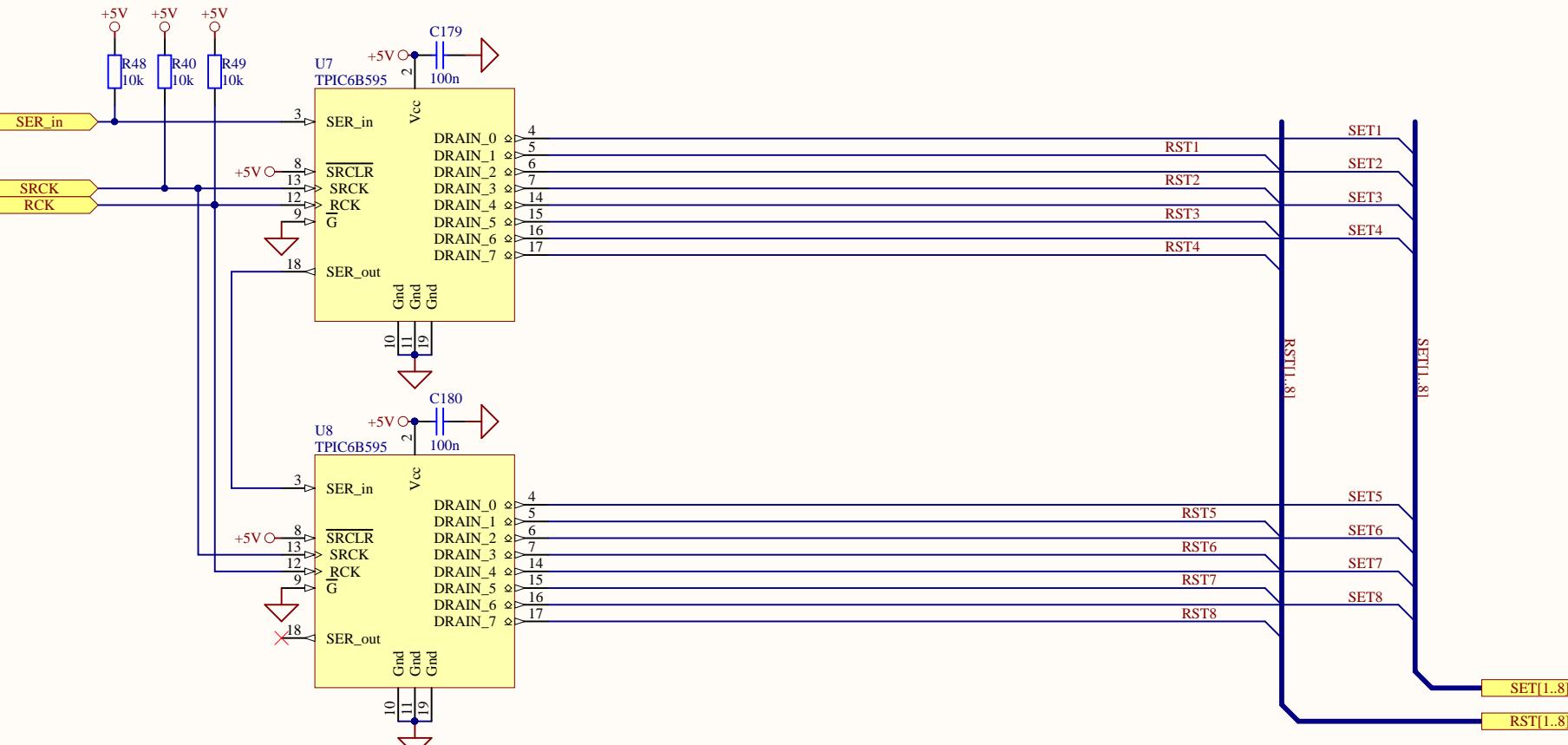


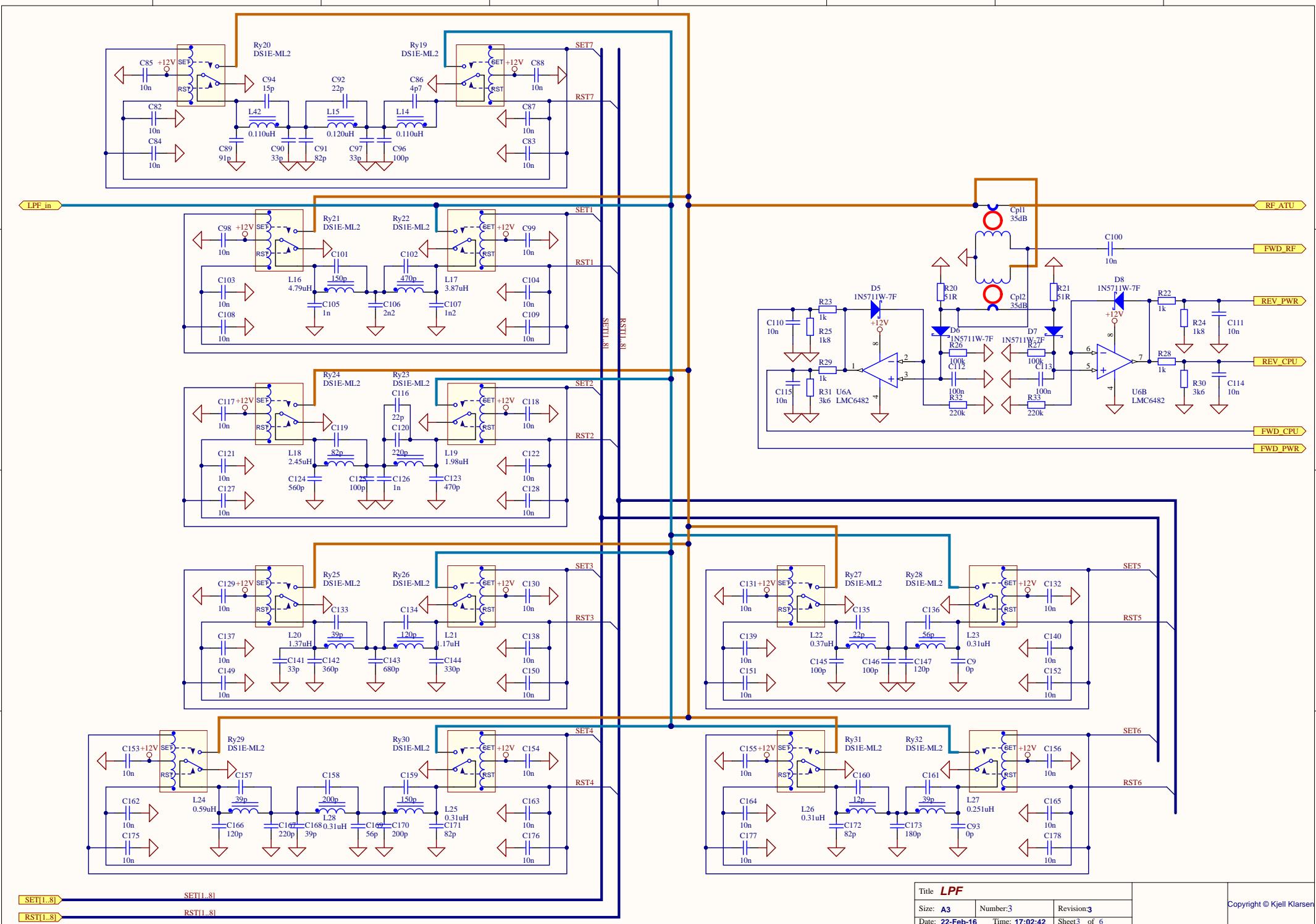
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 ▶ FIDucial1  
 MP2  
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 MP3  
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 MP4  
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 MP5



A

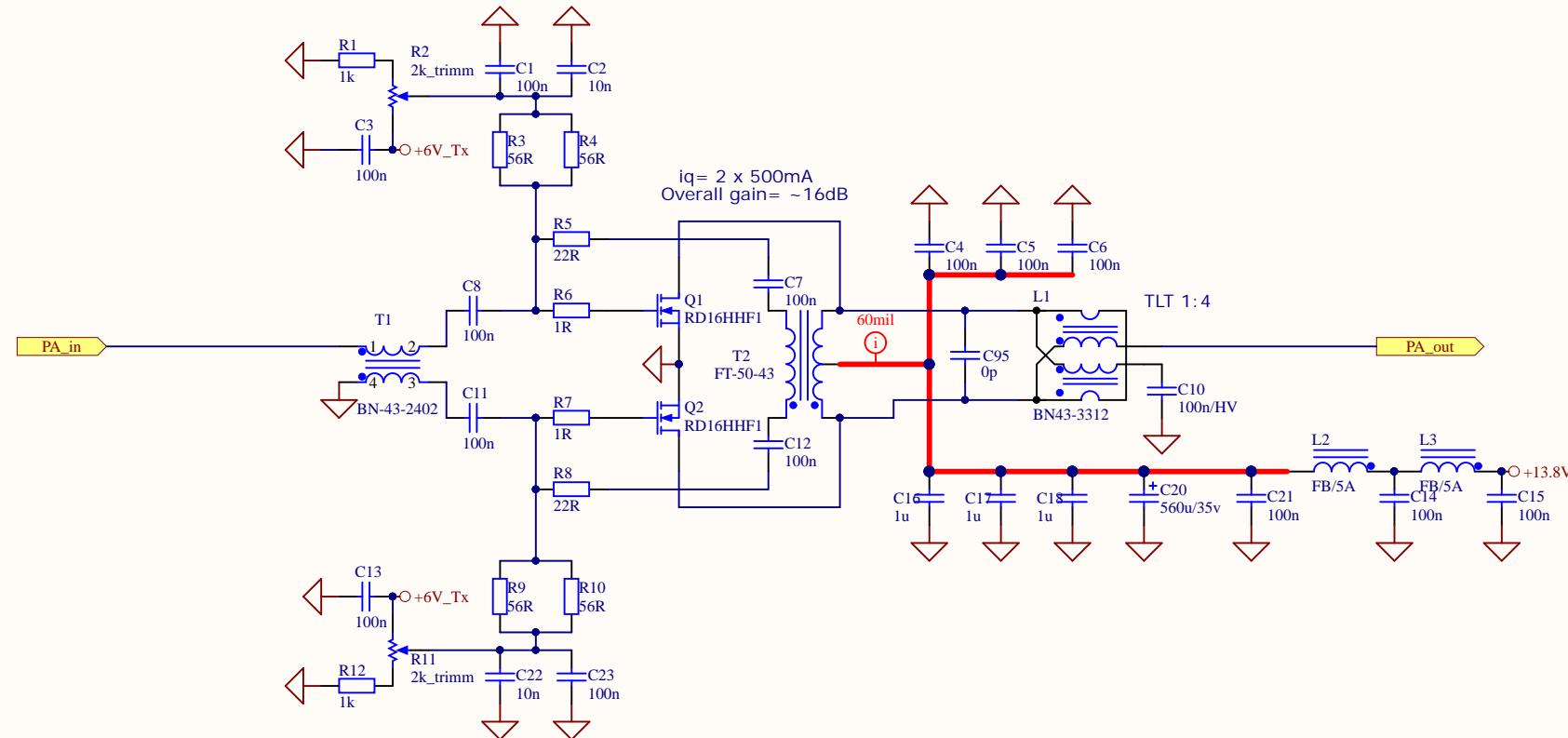
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A

A



B

B

C

C

D

D

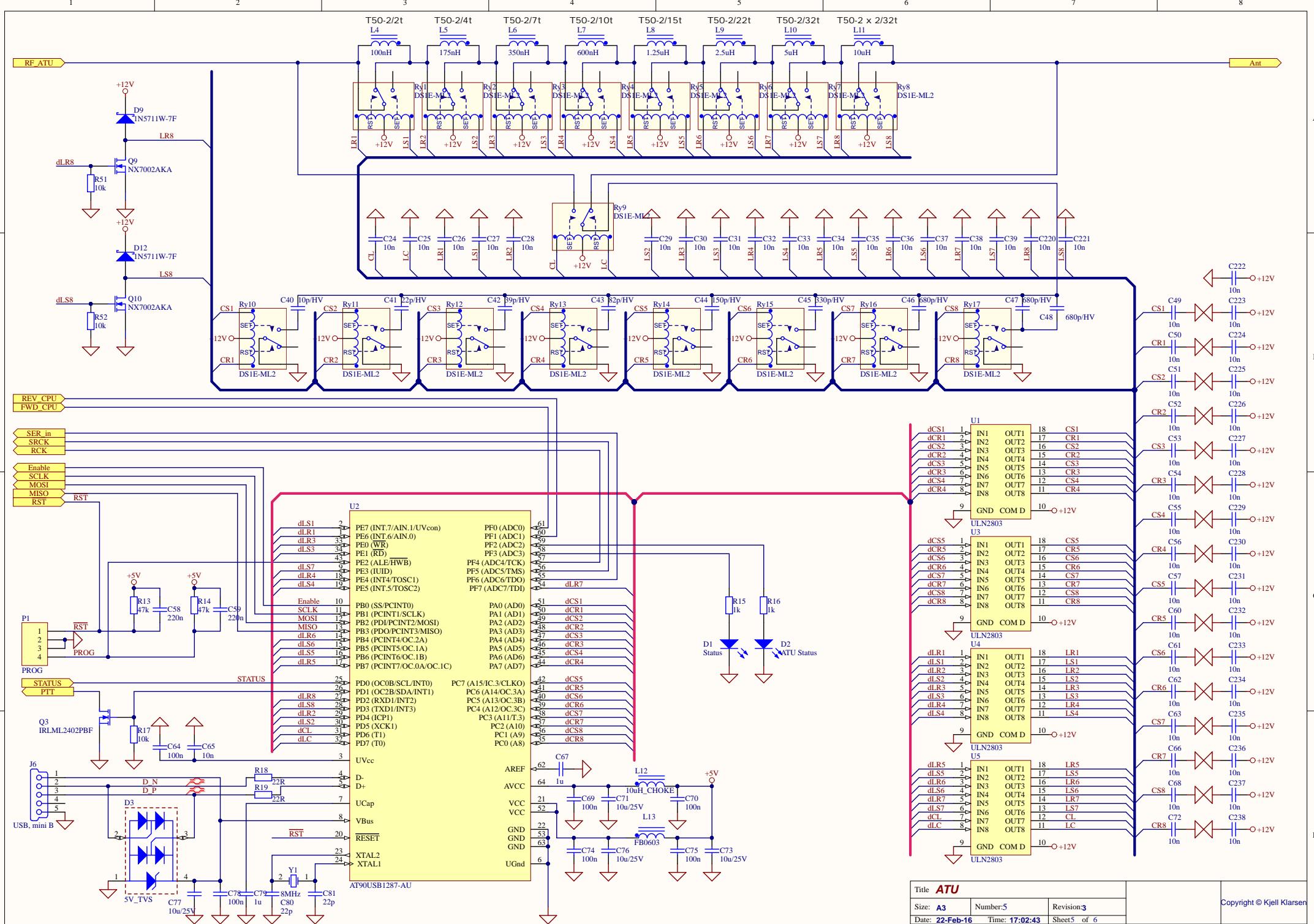
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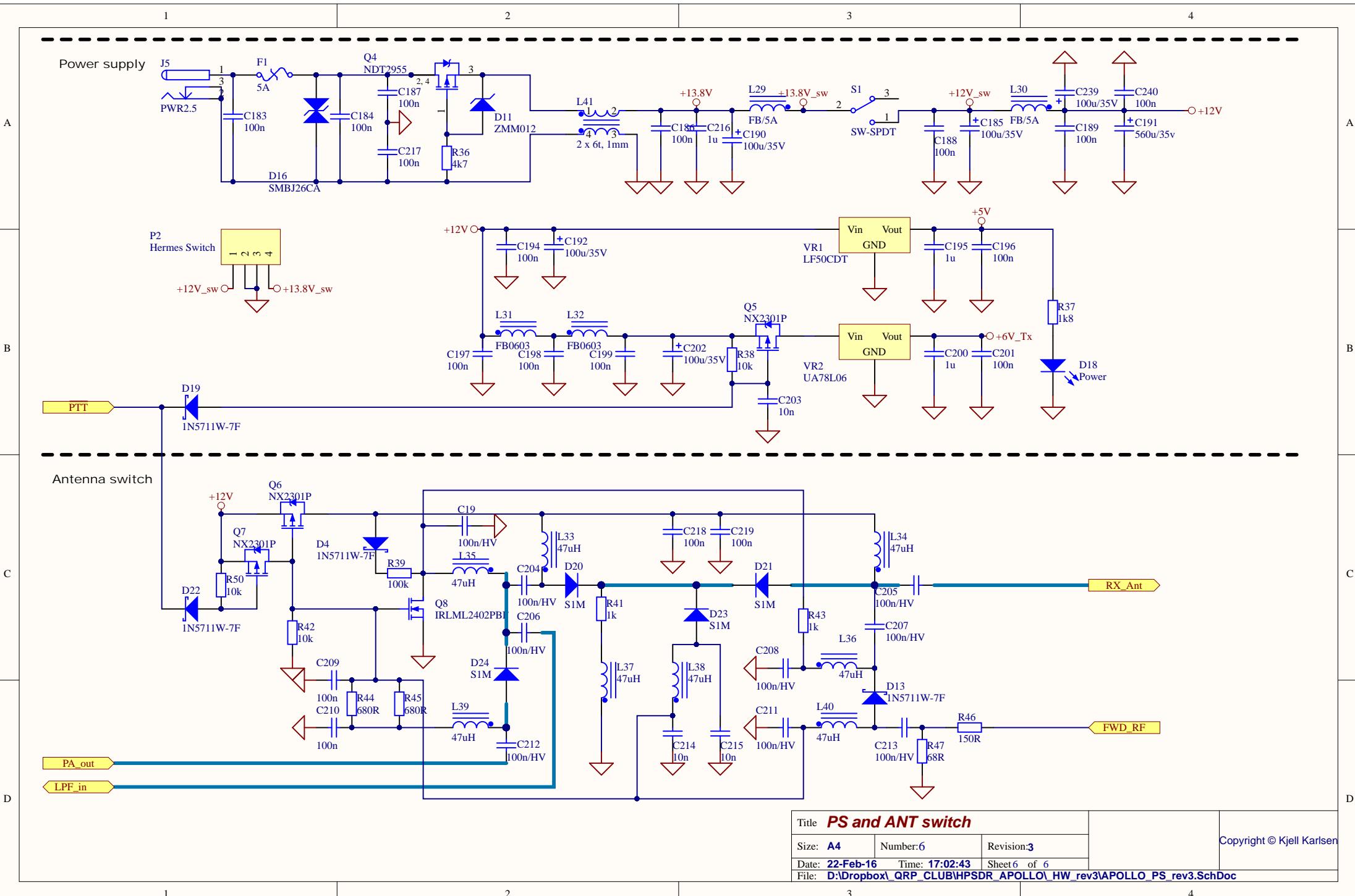
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Date: 22-Feb-16 Time: 17:02:42 Sheet 4 of 6

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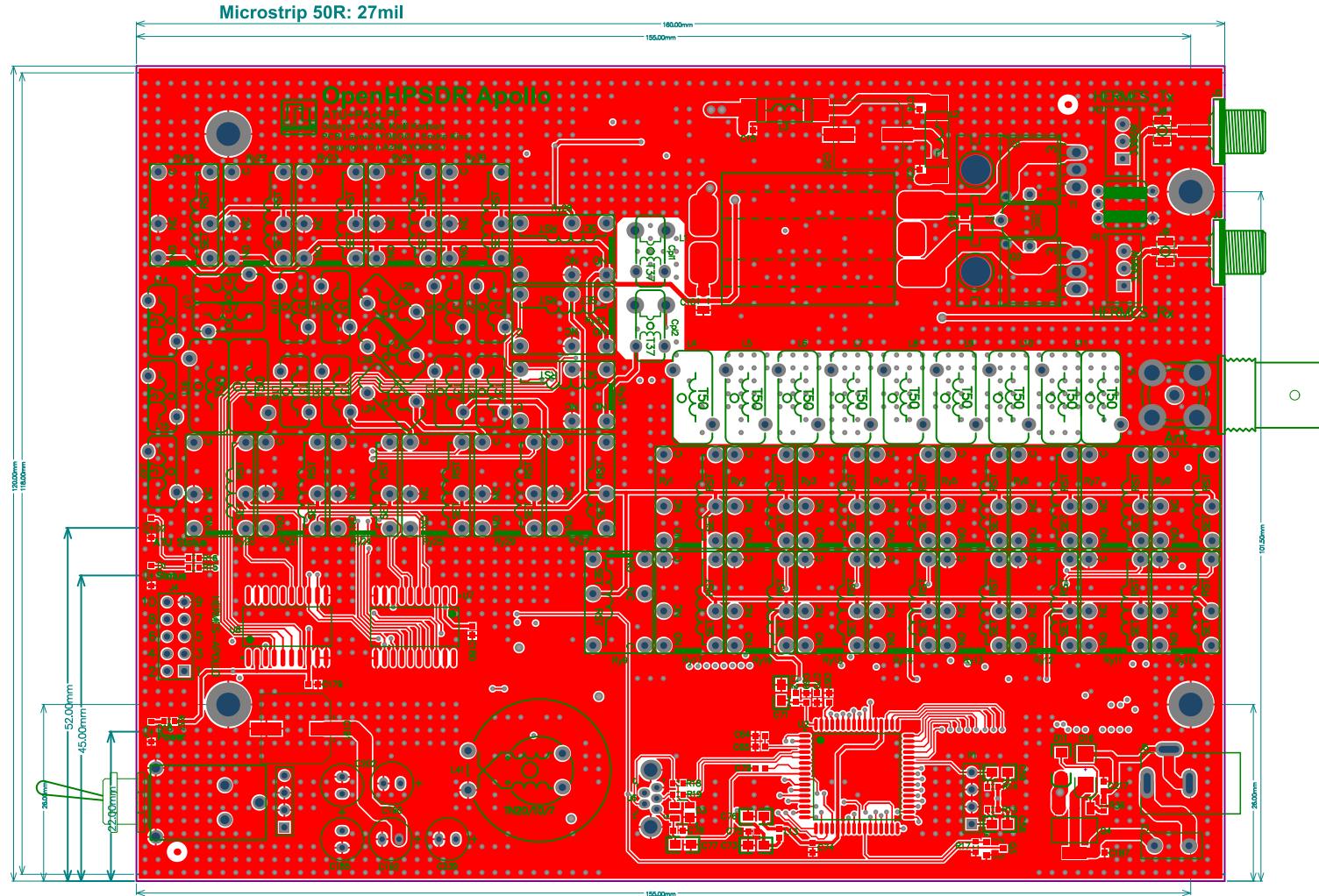
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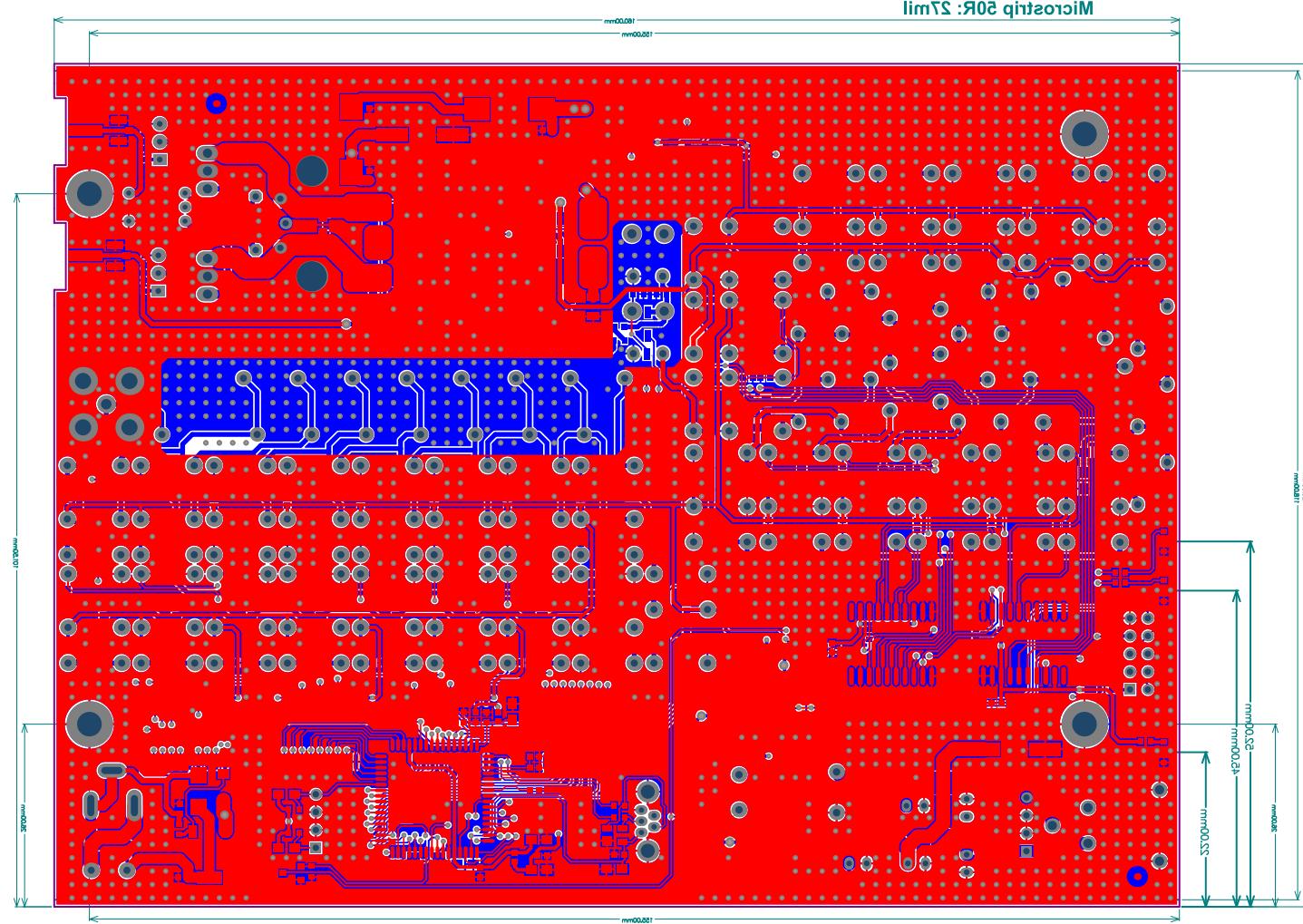




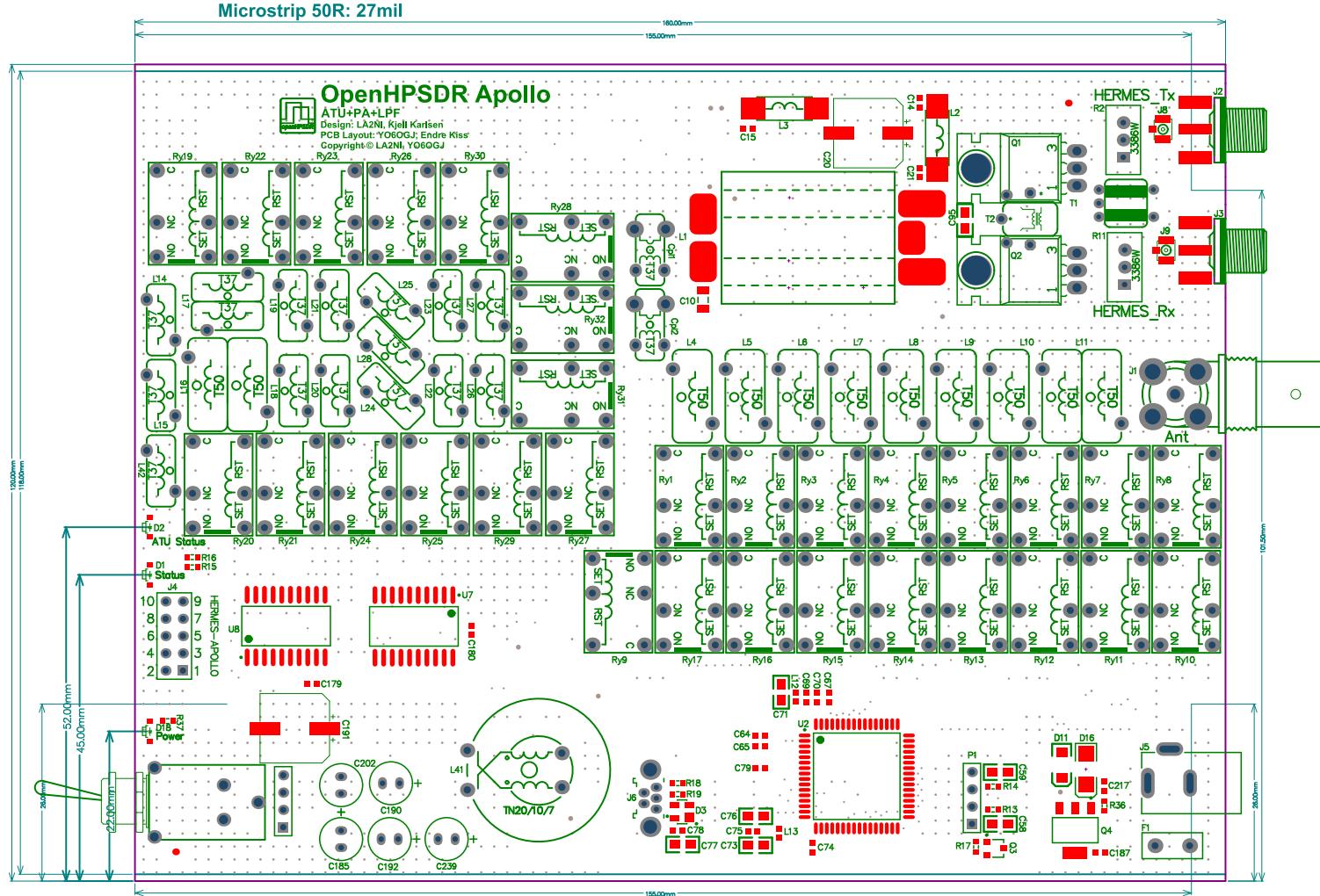
| Layer | Name           | Material      | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| 1     | Top Overlay    |               |           |          |                   |
| 2     | Top Solder     | Solder Resist | 0.40mil   | 3.5      |                   |
| 3     | Top Layer      | Copper        | 1.40mil   |          |                   |
| 4     | Dielectric1    | FR-4          | 14.00mil  | 4.08     |                   |
| 5     | Mid-Layer 1    | Copper        | 1.40mil   |          |                   |
| 6     | Dielectric2    | FR-4          | 27.95mil  | 4.08     |                   |
| 7     | Mid-Layer 2    | Copper        | 1.40mil   |          |                   |
| 8     | Dielectric3    | FR-4          | 14.00mil  | 4.08     |                   |
| 9     | Bottom Layer   | Copper        | 1.40mil   |          |                   |
| 10    | Bottom Solder  | Solder Resist | 0.40mil   | 3.5      |                   |
| 11    | Bottom Overlay |               |           |          |                   |



| Layer | Name           | Material      | Thickness | Consume | Board Layer Stack |
|-------|----------------|---------------|-----------|---------|-------------------|
| 1     | Top Overlay    |               |           |         |                   |
| 2     | Top Solder     | Solder Resist | 0.40 mil  | 3.5     |                   |
| 3     | Top Layer      | Copper        | 1.40 mil  |         |                   |
| 4     | Dielectric1    | FR-4          | 1.400 mil | 4.08    |                   |
| 5     | Mid-Layer 1    | Copper        | 1.40 mil  |         |                   |
| 6     | Dielectric2    | FR-4          | 2.735 mil | 4.08    |                   |
| 7     | Mid-Layer 2    | Copper        | 1.40 mil  |         |                   |
| 8     | Dielectric3    | FR-4          | 1.400 mil | 4.08    |                   |
| 9     | Bottom Layer   | Copper        | 1.40 mil  |         |                   |
| 10    | Bottom Solder  | Solder Resist | 0.40 mil  | 3.5     |                   |
| 11    | Bottom Overlay |               |           |         |                   |



| Layer | Name           | Material      | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| 1     | Top Overlay    |               |           |          |                   |
| 2     | Top Solder     | Solder Resist | 0.40mil   | 3.5      |                   |
| 3     | Top Layer      | Copper        | 1.40mil   |          |                   |
| 4     | Dielectric1    | FR-4          | 14.00mil  | 4.08     |                   |
| 5     | Mid-Layer 1    | Copper        | 1.40mil   |          |                   |
| 6     | Dielectric2    | FR-4          | 27.95mil  | 4.08     |                   |
| 7     | Mid-Layer 2    | Copper        | 1.40mil   |          |                   |
| 8     | Dielectric3    | FR-4          | 14.00mil  | 4.08     |                   |
| 9     | Bottom Layer   | Copper        | 1.40mil   |          |                   |
| 10    | Bottom Solder  | Solder Resist | 0.40mil   | 3.5      |                   |
| 11    | Bottom Overlay |               |           |          |                   |



| Layer | Name           | Material      | Thickness | Count/Unit | Board Layer Stack |
|-------|----------------|---------------|-----------|------------|-------------------|
| 1     | Top Overlay    |               |           |            |                   |
| 2     | Top Solder     | Solder Resist | 0.40μm    | 35         |                   |
| 3     | Top Layer      | Copper        | 1.40μm    | 408        |                   |
| 4     | Dielectric1    | FR-4          | 1.40μm    | 408        |                   |
| 5     | Mid-Layer 1    | Copper        | 1.40μm    | 408        |                   |
| 6     | Dielectric2    | FR-4          | 1.73μm    | 408        |                   |
| 7     | Mid-Layer 2    | Copper        | 1.40μm    | 408        |                   |
| 8     | Dielectric3    | FR-4          | 1.40μm    | 408        |                   |
| 9     | Bottom Layer   | Copper        | 1.40μm    | 408        |                   |
| 10    | Bottom Solder  | Solder Resist | 0.40μm    | 35         |                   |
| 11    | Bottom Overlay |               |           |            |                   |

